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MITSUBISHI IGBT MODULES
CM600DU-24NF

HIGH POWER SWITCHING USE

CM600DU-24NF



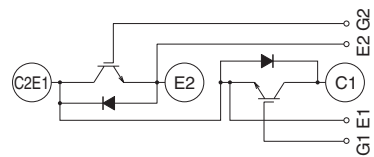
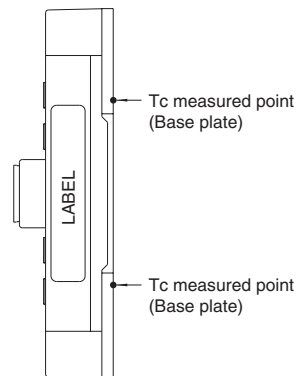
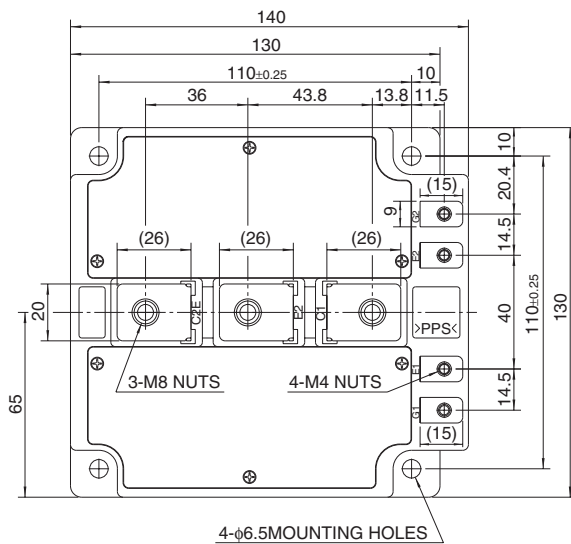
- IC 600A
- VCES 1200V
- Insulated Type
- 2-elements in a pack

APPLICATION

General purpose inverters & Servo controls, etc

OUTLINE DRAWING & CIRCUIT DIAGRAM

Dimensions in mm



CIRCUIT DIAGRAM

CM600DU-24NF

HIGH POWER SWITCHING USE

MAXIMUM RATINGS (Tj = 25°C, unless otherwise specified)

Symbol	Parameter	Conditions	Rating	Unit
V _{CES}	Collector-emitter voltage	G-E Short	1200	V
V _{GES}	Gate-emitter voltage	C-E Short	±20	V
I _C	Collector current	DC, T _c ' = 109°C ³	600	A
I _{CM}		Pulse (Note 2)	1200	A
I _E (Note 1)	Emitter current		600	A
I _{EM} (Note 1)		Pulse (Note 2)	1200	A
P _C (Note 3)	Total power dissipation	T _c = 25°C	2080	W
T _j	Junction temperature		-40 ~ +150	°C
T _{stg}	Storage temperature		-40 ~ +125	°C
V _{isol}	Isolation voltage	Terminals to base plate, f = 60Hz, AC 1 minute, RMS	2500	V
—	Mounting torque	Main terminals M8 screw	8.8 ~ 10.8	N • m
—		Mounting to heat sink M6 screw	3.5 ~ 4.5	N • m
—		G(E) Terminal M4 screw	1.3 ~ 1.7	N • m
	Weight	Typical value	1200	g

ELECTRICAL CHARACTERISTICS (Tj = 25°C, unless otherwise specified)

Symbol	Parameter	Conditions	Limits			Unit
			Min.	Typ.	Max.	
I _{CES}	Collector-emitter cut-off current	V _{CE} = V _{CES} , G-E short	—	—	1	mA
V _{GE(th)}	Gate-emitter threshold voltage	I _C = 60mA, V _{CE} = 10V	6	7	8	V
I _{GES}	Gate-emitter leakage current	±V _{GE} = V _{GES} , C-E short	—	—	0.5	µA
V _{CESat}	Collector-emitter saturation voltage	I _C = 600A, V _{GE} = 15V	—	1.95	2.65	V
		T _j = 25°C T _j = 125°C	—	2.15	—	
C _{ies}	Input capacitance	V _{CE} = 10V G-E short	—	—	140	nF
C _{oes}	Output capacitance		—	—	12	nF
C _{res}	Reverse transfer capacitance		—	—	2.7	nF
Q _G	Gate charge	V _{CC} = 600V, I _C = 600A, V _{GE} = 15V	—	4000	—	nC
t _{d(on)}	Turn-on delay time	V _{CC} = 600V, I _C = 600A V _{GE} = ±15V R _G = 1.0Ω, Inductive load I _E = 600A	—	—	800	ns
t _r	Rise time		—	—	180	ns
t _{d(off)}	Turn-off delay time		—	—	900	ns
t _f	Fall time		—	—	350	ns
t _{rr} (Note 1)	Reverse recovery time		—	—	300	ns
Q _{rr} (Note 1)	Reverse recovery charge		—	28	—	µC
V _{EC} (Note 1)	Emitter-collector voltage	I _E = 600A, G-E short	—	—	3.35	V
R _{th(j-c)Q}	Thermal resistance*1	IGBT part (1/2 module)	—	—	0.06	K/W
R _{th(j-c)R}		FWDi part (1/2 module)	—	—	0.11	K/W
R _{th(c-f)}	Contact thermal resistance	Case to heat sink, Thermal compound Applied*2 (1/2 module)	—	0.019	—	K/W
R _{th(j-c)Q}	Thermal resistance	Case temperature measured point is just under the chips	—	—	0.023*3	K/W
R _G	External gate resistance		1.0	—	10	Ω

*1 : Case temperature (T_c) measured point is shown in page OUTLINE DRAWING.

*2 : Typical value is measured by using thermally conductive grease of λ = 0.9[W/(m • K)].

*3 : Case temperature (T_c) measured point is just under the chips.

If you use this value, R_{th(f-a)} should be measured just under the chips.

Note 1. I_E, V_{EC}, t_{rr} & Q_{rr} represent characteristics of the anti-parallel, emitter-collector free-wheel diode (FWDi).

2. Pulse width and repetition rate should be such that the device junction temperature (T_j) does not exceed T_{jmax} rating.

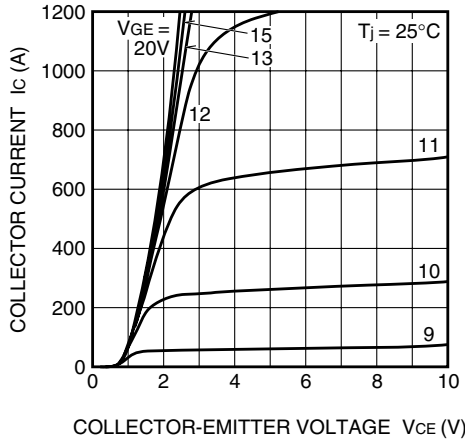
3. Junction temperature (T_j) should not increase beyond 150°C.

CM600DU-24NF

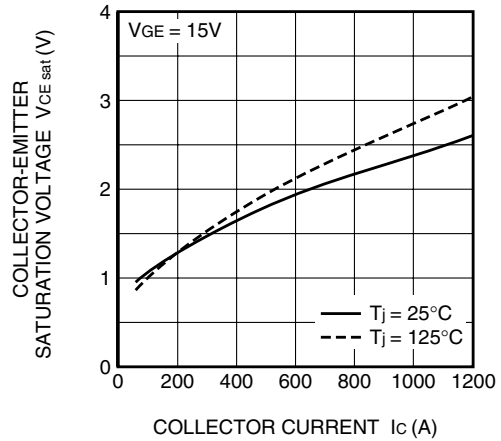
HIGH POWER SWITCHING USE

PERFORMANCE CURVES

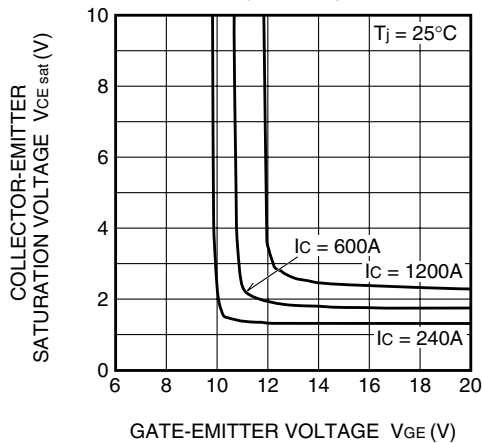
OUTPUT CHARACTERISTICS (TYPICAL)



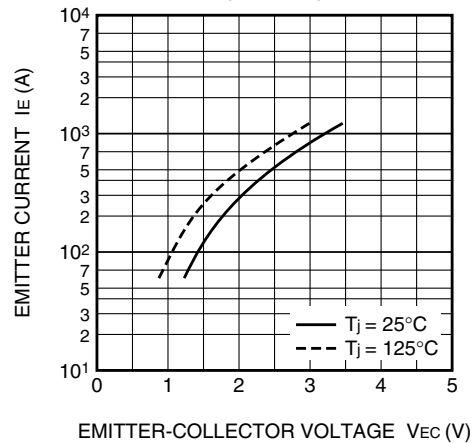
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



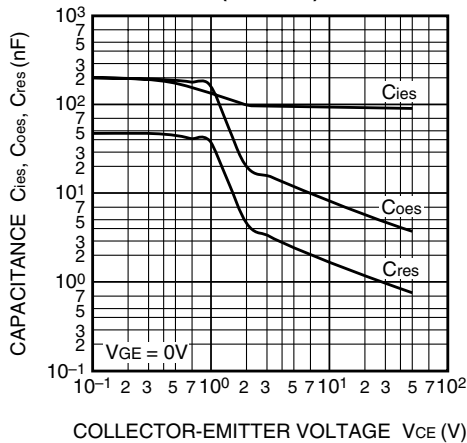
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



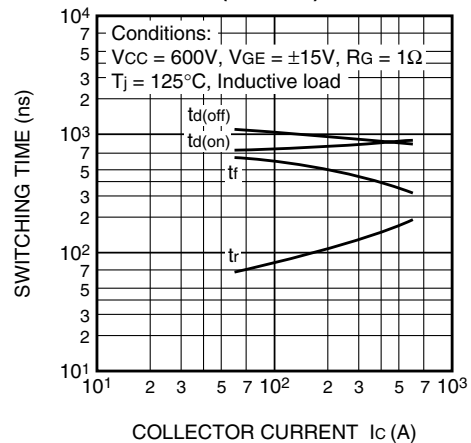
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



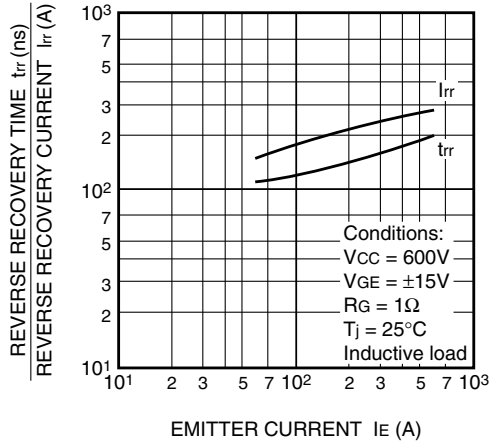
CAPACITANCE-VCE CHARACTERISTICS (TYPICAL)



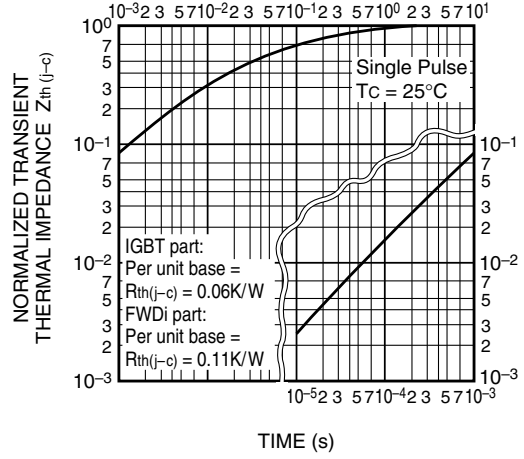
HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)



REVERSE RECOVERY CHARACTERISTICS OF FREE-WHEEL DIODE (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT part & FWDi part)



GATE CHARGE CHARACTERISTICS (TYPICAL)

